

Attachment No. 2

Minutes of the CE-2.2 Subcommittee on Sockets 24 – 25 September 2007 San Antonio, TX

Facilitator Carl Fritz welcomed everyone, and said that the meeting would be conducted following the published agenda.

It is noted that the CE-2.0 committee will simultaneously approve all actions taken by the subcommittee.

1. Approval of the 16 – 17 April 2007 Minutes

The minutes of the 16 – 17 April 2007 meeting in San Diego, CA were approved. Moved by Bob Druckenmiller and seconded by Ralph Antonelli. The motion was unanimously moved and approved.

2. SPECIFICATIONS BY PROJECT NUMBERS

A. SP-4965, EIA-540B0AE, Detail Land Grid Array (Contech Research is sponsor)

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

B. SP-4970, EIA-540DAAA-A, Detail, DIP

At EDEC for approval.

C. SP-4971, EIA-700A0AB, 68-pin Memory Card Connector

At EDEC for approval.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

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E. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

A second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

F. PN-5123, EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

After much discussion and review of several e-mails between Tom Peel, Max Peel and John Healey it was moved by Bob Druckenmiller and seconded by Ralph Antonelli to go out on letter ballot. The motion was approved.

3. SPECIFICATIONS AWAITING PROJECT NUMBERS

None.

4. NEW BUSINESS

Prepared by:

Carl Fritz, Facilitator, CE-2.2